



### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
40V	5.0m $\Omega$ @10V	60A
	7.9m $\Omega$ @4.5V	

### Feature

- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100%  $\Delta V_{DS}$  Tested

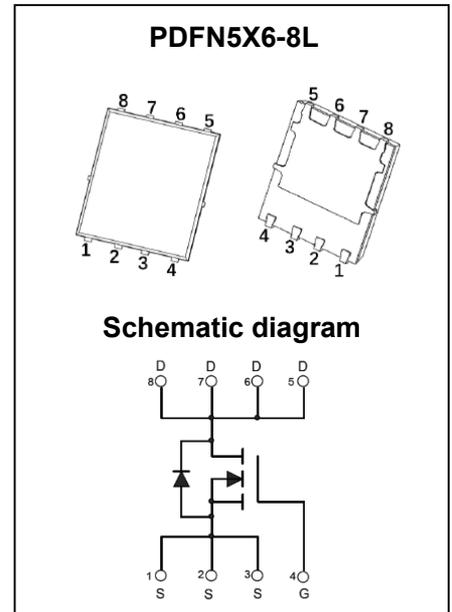
### Application

- Power Switching Application
- DC/DC Converter

### MARKING:



T050N04L = Device Code  
XX = Date Code  
Solid Dot = Green Indicator



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	40	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ\text{C}$	$I_D$	60 A
	$T_C = 100^\circ\text{C}$	$I_D$	39 A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	240	A
Single Pulsed Avalanche Current <sup>3</sup>	$I_{AS}$	19	A
Single Pulsed Avalanche Energy <sup>3</sup>	$E_{AS}$	90	mJ
Power Dissipation <sup>5</sup>	$T_C = 25^\circ\text{C}$	$P_D$	55 W
Thermal Resistance from Junction to Ambient <sup>6</sup>	$R_{\theta JA}$	58	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.3	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

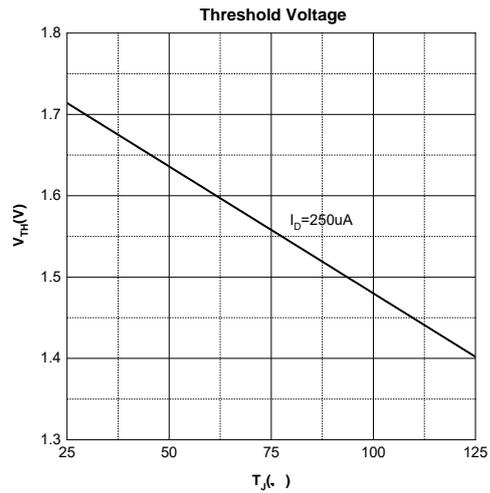
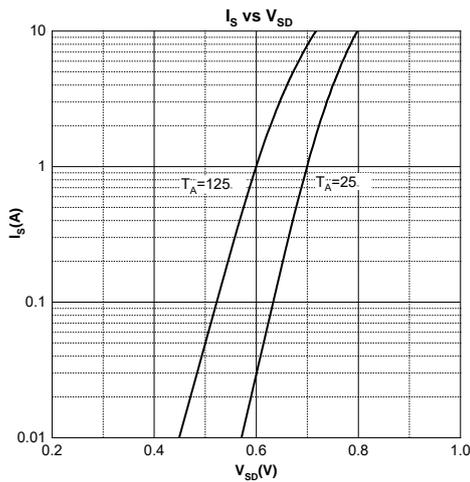
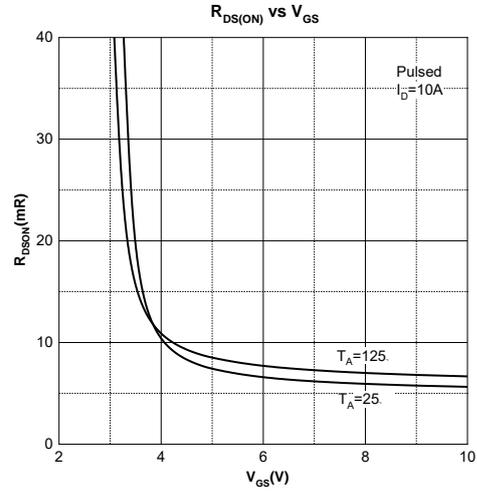
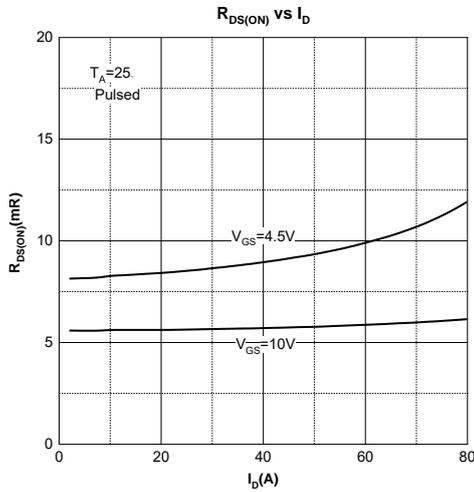
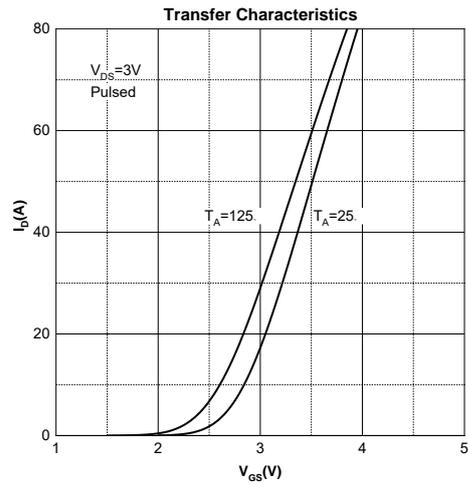
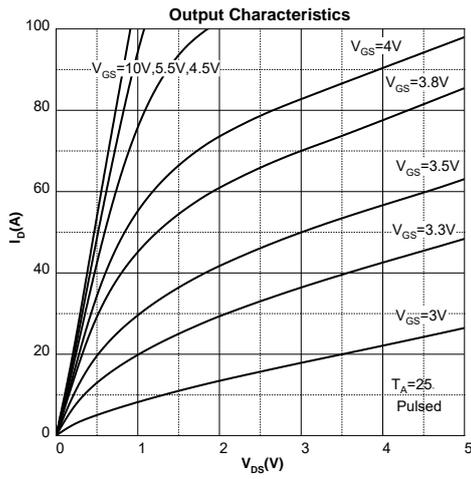
## MOSFET ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

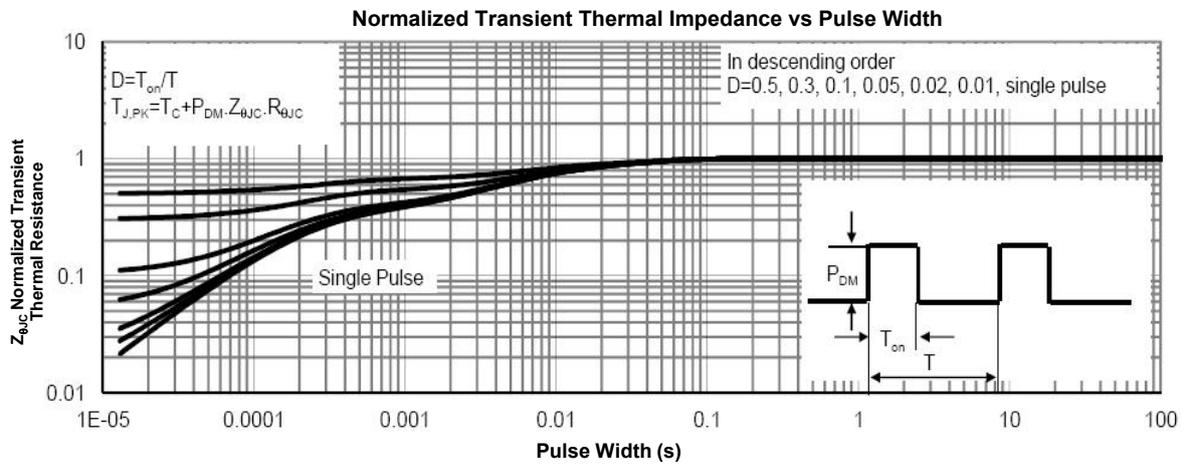
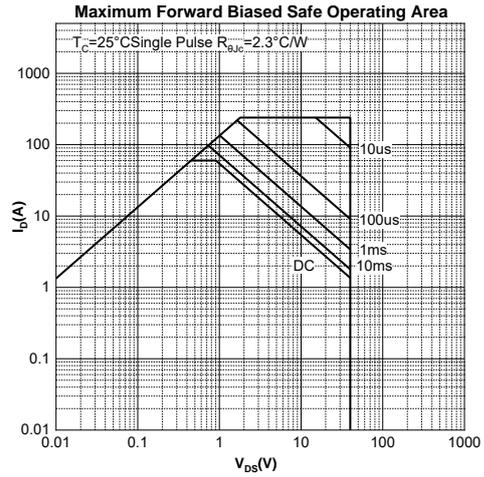
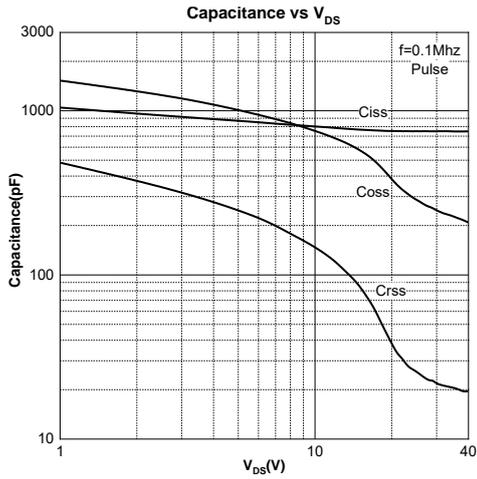
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 40V, V_{GS} = 0V$			1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>4</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.6	3	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 10A$		5.0	7.0	m $\Omega$
		$V_{GS} = 4.5V, I_D = 10A$		7.9	11.0	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V, f = 0.1MHz$		746		pF
Output Capacitance	$C_{oss}$			381		
Reverse Transfer Capacitance	$C_{rss}$			38		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 0.1MHz$		3.3		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 20V, V_{GS} = 10V, I_D = 10A$		18		nC
Gate-source Charge	$Q_{gs}$			2.1		
Gate-drain Charge	$Q_{gd}$			5.6		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 20V, V_{GS} = 10V, R_G = 1.6\Omega, I_D = 20A$		10		ns
Turn-on Rise Time	$t_r$			32		
Turn-off Delay Time	$t_{d(off)}$			27		
Turn-off Fall Time	$t_f$			12		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 10A$			1.2	V

Notes :

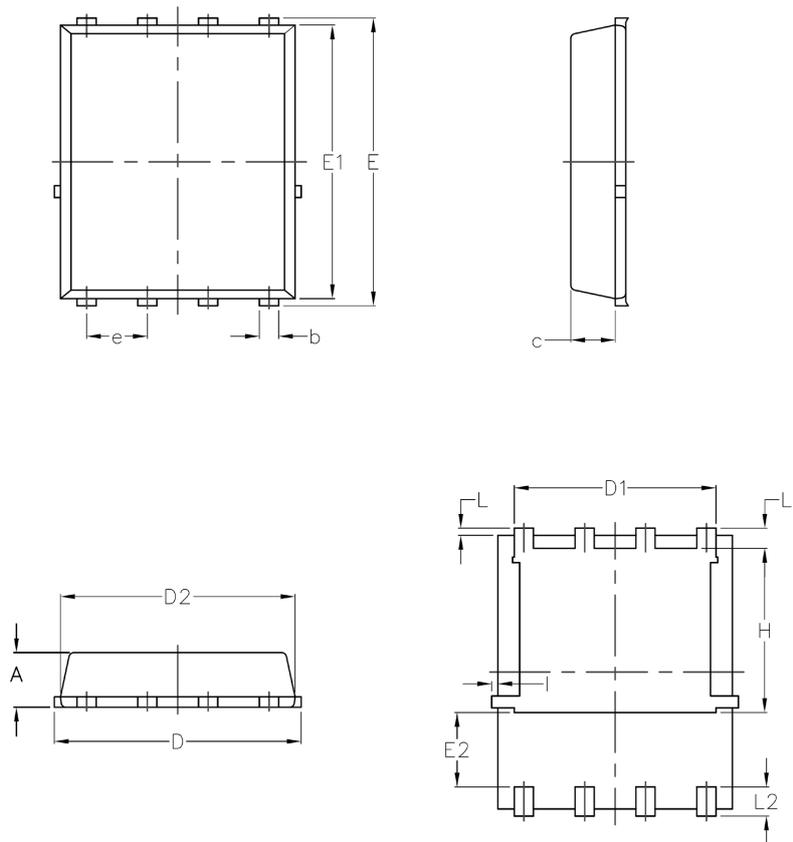
1. The maximum current rating is limited by package. And device mounted on a large heatsink
2. Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
3.  $E_{AS}$  condition:  $V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
4. Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ . And device mounted on a large heatsink
6. Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

**Typical Characteristics**





## PDFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.030	1.170	0.041	0.046
b	0.340	0.480	0.013	0.019
c	0.824	0.970	0.032	0.038
D	4.800	5.400	0.189	0.213
D1	4.110	4.310	0.162	0.170
D2	4.800	5.000	0.189	0.197
E	5.950	6.150	0.234	0.242
E1	5.650	5.850	0.222	0.230
E2	1.400	-	0.055	-
e	1.270BSC		0.050BSC	
L	0.050	0.250	0.002	0.010
L1	0.380	0.500	0.015	0.020
L2	0.380	0.710	0.015	0.028
H	3.300	3.500	0.130	0.138
I	-	0.180	-	0.007